L Number	Hits	Search Text	DB	Time stamp
1	21125	(smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27
2	3248	<pre>(least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27
3	361	((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27 09:46
4	742	((least stacked multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (resin encapsulant epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27 09:58
5	576	(((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (resin encapsulant epoxy)) not	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27 09:47
		(((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and package)	TBN_1DB	
6	105	(bump ball flip flipchip) and ((((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and (resin encapsulant epoxy)) not (((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27
7	2241072	adj circuit)))) and package)) (flipchip flip die chip dice ic semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/27 09:53
8	403564	(least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit)))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/27 09:56
9	38492	<pre>(bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27 10:31
10	2438	((bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))))) same (resin encapsulant epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27
11	15795	(smooth blunt curved abrupt frank dull) with (die chip dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/27

				2000/07/27
12	62	((smooth blunt curved abrupt frank dull) with (die chip dice ic (integrated adj circuit))) and (((bump ball flip flipchip) same ((least stacked multi	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/27 10:01
		multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))))) same (resin	IBM_TDB	
13	60	<pre>encapsulant epoxy)) (((smooth blunt curved abrupt frank dull) with (die chip dice ic (integrated adj</pre>	USPAT; US-PGPUB;	2002/07/27 10:26
		<pre>circuit))) and (((bump ball flip flipchip) same ((least stacked multi multiple plurality) same ((flipchip flip die chip dice ic semiconductor (integrated adj circuit))))) same (resin encapsulant epoxy))) not ((bump ball flip flipchip) and ((((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj</pre>	EPO; JPO; DERWENT; IBM_TDB	
		circuit))) and (resin encapsulant epoxy)) not (((least stacked multi multiple plurality) same ((smooth blunt curved abrupt frank dull) with (die chip dice ic semiconductor (integrated adj circuit)))) and package)))		
14	2534	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/27 10:26
2.5	1,600	257/606	IBM_TDB USPAT;	2002/07/27
15	1609	257/686	US-PGPUB; EPO; JPO; DERWENT;	10:26
16	751	257/685	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/27 10:26
17	1434	257/777	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/27 10:26
18	2360	257/778	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/27 10:26
19	1583	257/738	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/07/27
20	1970	257/737	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/07/27 10:26
21	7081	257/723 257/686 257/685 257/777 257/778 257/738 257/737	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/07/27 10:27
22	111413	(smooth blunt curved abrupt frank dull shape irregular) with (die chip dice ic semiconductor (integrated adj circuit))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/07/27
		Semiconductor (integrated adj circuit))	DERWENT; IBM_TDB	

23	1552	((smooth blunt curved abrupt frank dull	USPAT;	2002/07/27
		shape irregular) with (die chip dice ic	US-PGPUB;	10:29
		semiconductor (integrated adj circuit)))	EPO; JPO;	
		and (257/723 257/686 257/685 257/777	DERWENT;	
		257/778 257/738 257/737)	IBM_TDB	
24	90288	((smooth blunt curved abrupt frank dull	USPAT;	2002/07/27
		shape irregular) with (die chip dice ic	US-PGPUB;	10:29
		semiconductor (integrated adj circuit)))	EPO; JPO;	
		not ((smooth blunt curved abrupt frank	DERWENT;	
		dull) with (die chip dice ic	IBM_TDB	
0.5	1250	semiconductor (integrated adj circuit)))	110 D D D	2002 (07 (27
25	1359	(((smooth blunt curved abrupt frank dull	USPAT;	2002/07/27
		shape irregular) with (die chip dice ic	US-PGPUB;	10:29
		semiconductor (integrated adj circuit)))	EPO; JPO;	ļ
		not ((smooth blunt curved abrupt frank dull) with (die chip dice ic	DERWENT;	
		semiconductor (integrated adj circuit))	IBM_TDB	
)) and (257/723 257/686 257/685 257/777		[
		257/778 257/738 257/737)		
26	1299	(least stacked multi multiple plurality)	USPAT;	2002/07/27
20	1000	and ((((smooth blunt curved abrupt frank	US-PGPUB;	10:30
		dull shape irregular) with (die chip dice	EPO; JPO;	
		ic semiconductor (integrated adj	DERWENT;	
		circuit))) not ((smooth blunt curved	IBM TDB	
	1	abrupt frank dull) with (die chip dice ic	_	
		semiconductor (integrated adj circuit))		
)) and (257/723 257/686 257/685 257/777	ĺ	
		257/778 257/738 257/737))		
27	983	((least stacked multi multiple plurality)	USPAT;	2002/07/27
		and ((((smooth blunt curved abrupt frank	US-PGPUB;	10:31
		dull shape irregular) with (die chip dice	EPO; JPO;	
		ic semiconductor (integrated adj	DERWENT;	
		circuit))) not ((smooth blunt curved	IBM_TDB	
		abrupt frank dull) with (die chip dice ic		
		semiconductor (integrated adj circuit))		
)) and (257/723 257/686 257/685 257/777		
		257/778 257/738 257/737))) and (resin		
28	200	encapsulant epoxy)	IICDAM.	2002/07/27
28	755	(bump ball flip flipchip) and (((least	USPAT;	2002/07/27
		stacked multi multiple plurality) and ((((smooth blunt curved abrupt frank dull	US-PGPUB;	10:32
			EPO; JPO;	
		shape irregular) with (die chip dice ic semiconductor (integrated adj circuit)))	DERWENT; IBM TDB	
		not ((smooth blunt curved abrupt frank	1011_100	
	1 1 1 1 1	dull) with (die chip dice ic		
		semiconductor (integrated adj circuit))		
	1 14)) and (257/723 257/686 257/685 257/777		
		257/778 257/738 257/737))) and (resin		
		encapsulant epoxy))		
		encapsurant epoxy))		